

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE2004Y uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =20V,I_D =4A

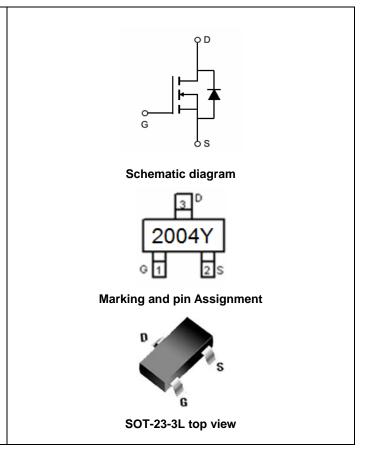
 $R_{DS(ON)} < 24m\Omega @ V_{GS} = 4.5V$

 $R_{DS(ON)}$ < 32m Ω @ V_{GS} =2.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2004Y	NCE2004Y	SOT23-3L	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	I _D	4	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	2.8	Α
Pulsed Drain Current	I _{DM}	20	Α
Maximum Power Dissipation	P _D	1.0	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	125	°C/W
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Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	22	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)	·						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.5	0.7	0.9	V	
Drain Course On State Besistance	Б	V_{GS} =4.5 V , I_D =4 A	-	19	24	0	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =3A	-	25	32	mΩ	
Forward Transconductance	g FS	V _{DS} =5V,I _D =4A	20	-	-	S	
Dynamic Characteristics (Note4)			•				
Input Capacitance	C _{lss}	\/ 40\/\\ 0\/	-	550	-	PF	
Output Capacitance	C _{oss}	V_{DS} =10V, V_{GS} =0V, F=1.0MHz	-	110	-	PF	
Reverse Transfer Capacitance	C _{rss}	r=1.0WInz	-	85	-	PF	
Switching Characteristics (Note 4)	·						
Turn-on Delay Time	t _{d(on)}		-	8	-	nS	
Turn-on Rise Time	t _r	V_{DD} =10 V , I_D =4 A	-	9	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GEN} =4.5 V , R_G =6 Ω	-	15	-	nS	
Turn-Off Fall Time	t _f		-	4	-	nS	
Total Gate Charge	Qg	V _{DS} =10V,I _D =4A,	-	6	-	nC	
Gate-Source Charge	Q _{gs}	$V_{DS}=10V,I_{D}=4A,$ $V_{GS}=4.5V$	-	1.5	-	nC	
Gate-Drain Charge	Q _{gd}	VGS-4.3V	-	1.6	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =4A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	4	Α	

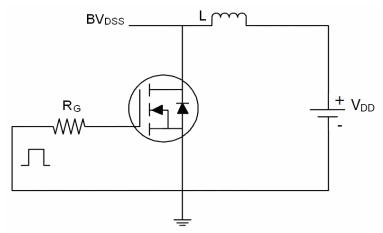
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

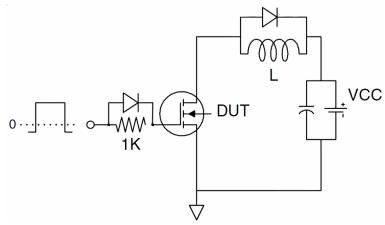


Test Circuit

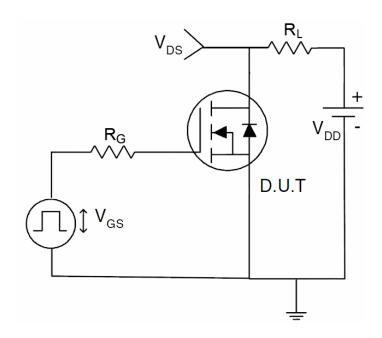
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:

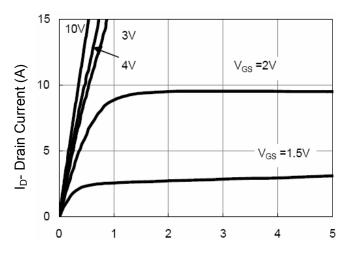


3) Switch Time Test Circuit:



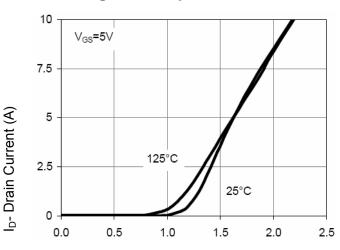


Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

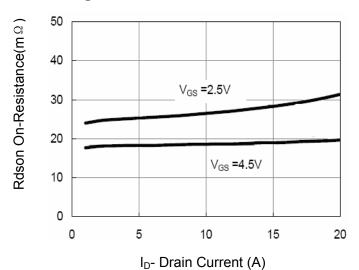
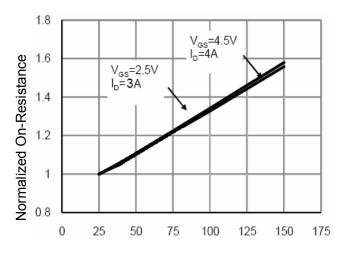


Figure 3 Rdson- Drain Current



T_J-Junction Temperature(°C)

Figure 4 Rdson-JunctionTemperature

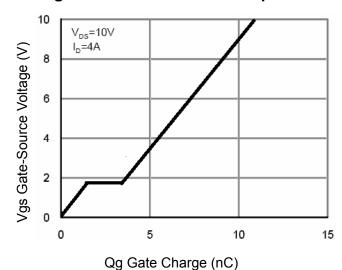
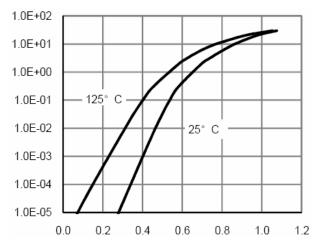


Figure 5 Gate Charge

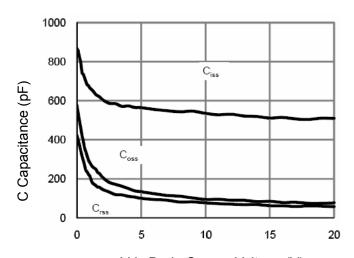


Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

TJ(°C)





Vds Drain-Source Voltage (V)



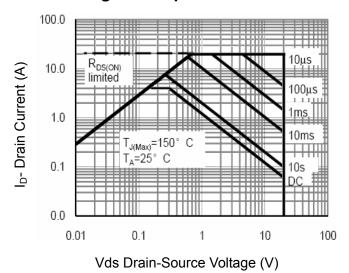
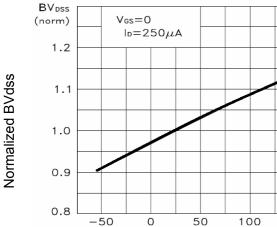


Figure 8 Safe Operation Area



 T_J -Junction Temperature($^{\circ}$ C)

Figure 9 BV_{DSS} vs Junction Temperature

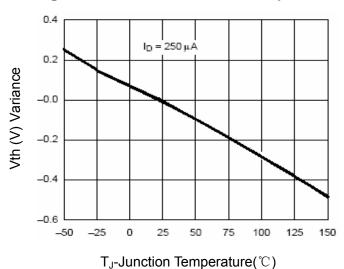


Figure 10 V_{GS(th)} vs Junction Temperature

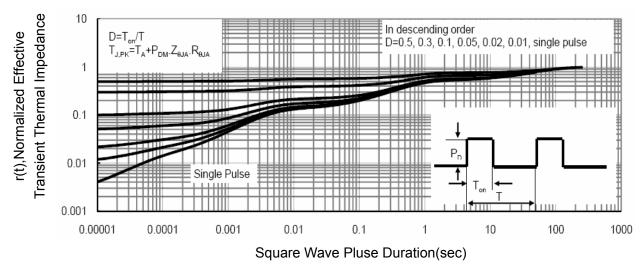
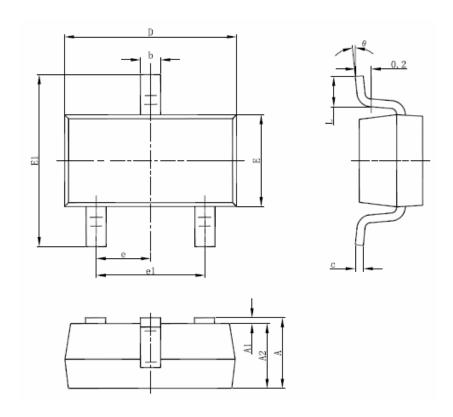


Figure 11 Normalized Maximum Transient Thermal Impedance



SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
e	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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